



IS410 Lead-free Epoxy Laminate and Prepreg

IS410 is a high-performance FR-4 epoxy laminate and prepreg system designed to support the printed circuit board industry's requirements for higher levels of reliability and the trend to use lead-free solder.

Isola's IS410 has a glass transition temperature (Tg) of 180°C and is specially formulated for superior performance through multiple thermal excursions, passing 6X solder tests at 288°C. IS410 is optimized for enhanced drilling performance allowing high aspect ratio holes of ≤10 mils. Its unique resin chemistry provides CAF resistance with the benefit of long-term reliability of boards built with small feature designs.

www.isola-group.com/products/IS410

ORDERING INFORMATION:

Contact your local sales representative or visit www.isola-group.com for further information.

Isola Group
3100 West Ray Road
Suite 301
Chandler, AZ 85226
Phone: 480-893-6527
Fax: 480-893-1409
info@isola-group.com

Isola Asia Pacific (Hong Kong) Ltd.
Unit 3512 - 3522, 35/F
No. 1 Hung To Road, Kwun Tong,
Kowloon, Hong Kong
Phone: 852-2418-1318
Fax: 852-2418-1533
info.hkg@isola-group.com

Isola GmbH
Isola Strasse 2
D-52348 Düren, Germany
Phone: 49-2421-8080
Fax: 49-2421-808164
info-dur@isola-group.com

High Performance

IS410 Data Sheet

Tg 180, Td 350
Dk 3.97, Df 0.02
/21 /24 /26 /121 /124
/129

Features

- High Thermal Performance
 - ▶ Tg: 180°C (DSC)
 - ▶ Td: 350°C (TGA @ 5% wt loss)
 - ▶ Superior performance through multiple thermal excursions – passes 6x @ 288°C
- T260: 50 minutes
- T288: 10 minutes
- RoHS Compliant
- Enhanced Drilling Performance for High Aspect PTH
 - ▶ Greater than 10 to 1 aspect ratio
 - ▶ Optimized for drilling small holes (≤10 mils)
- Core Material Standard Availability
 - ▶ Thickness: 0.002" (0.05 mm) to 0.125" (3.2 mm)
 - ▶ Available in full size sheet or panel form
- Prepreg Standard Availability
 - ▶ Roll or panel form
 - ▶ Tooling of prepreg panels available
- Copper Foil Type Availability
 - ▶ Standard HTE Grade 3
 - ▶ RTF (Reverse Treat Foil)
- Copper Weights
 - ▶ ½, 1 and 2 oz (18, 35 and 70 µm) available
 - ▶ Heavier copper available upon request
 - ▶ Thinner copper foil available upon request
- Glass Fabric Availability
 - ▶ Standard E-glass
 - ▶ Square weave glass fabric available
- Industry Approvals
 - ▶ IPC-4101D WAM1 /21 /24 /26 /121 /124 /129 (IPC-4101C /21 /24 /26 /28 /121 /124 /129)
 - ▶ UL - File Number E41625

IS410 Typical Values

Property		Typical Values		
		Typical Value	Units	Test Method
			Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		180	°C	2.4.25
Decomposition Temperature (Td) by TGA @ 5% weight loss		350	°C	ASTM D3850
T260		50	Minutes	ASTM D3850
T288		10	Minutes	ASTM D3850
CTE, Z-axis	A. Pre-Tg	55	ppm/°C	2.4.24
	B. Post-Tg	250		
CTE, X-, Y-axes	A. Pre-Tg	11	ppm/°C	2.4.24
	B. Post-Tg	13		
Z-axis Expansion (50-260°C)		3.5	%	2.4.24
Thermal Conductivity		0.5	W/mK	ASTM D5930
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched	Pass	Rating	2.4.13.1
	B. Etched			
Dk, Permittivity (Laminate & prepreg as laminated) Tested at 50% resin	A. @ 100 MHz (HP4285A)	3.96	-	2.5.5.3
	B. @ 1 GHz (HP4291A)	3.90		2.5.5.9
	C. @ 2 GHz (Bereskin Stripline)	3.97		2.5.5.5
	D. @ 5 GHz (Bereskin Stripline)	3.87		2.5.5.5
	E. @ 10 GHz (Bereskin Stripline)	3.87		2.5.5.5
Df, Loss Tangent (Laminate & prepreg as laminated) Tested at 50% resin	A. @ 100 MHz (HP4285A)	0.0149	-	2.5.5.3
	B. @ 1 GHz (HP4291A)	0.0189		2.5.5.9
	C. @ 2 GHz (Bereskin Stripline)	0.0200		2.5.5.5
	D. @ 5 GHz (Bereskin Stripline)	0.0230		2.5.5.5
	E. @ 10 GHz (Bereskin Stripline)	0.0230		2.5.5.5
Volume Resistivity	A. 96/35/90	-	MΩ-cm	2.5.17.1
	B. After moisture resistance	5.0x10 ⁸		
	C. At elevated temperature	3.6x10 ⁸		
Surface Resistivity	A. 96/35/90	-	MΩ	2.5.17.1
	B. After moisture resistance	8.0x10 ⁶		
	C. At elevated temperature	4.5x10 ⁸		
Dielectric Breakdown		>50	kV	2.5.6
Arc Resistance		129	Seconds	2.5.1
Electric Strength (Laminate & prepreg as laminated)		44 (1100)	kV/mm (V/mil)	2.5.6.2
Comparative Tracking Index (CTI)		3 (175-249)	Class (Volts)	UL-746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile – all copper weights >17 microns	1.14 (6.5)	N/mm (lb/inch)	2.4.8
	B. Standard profile copper	-		2.4.8.2
	1. After thermal stress	1.225 (7.0)		2.4.8.3
	2. At 125°C (257°F)	1.14 (6.5)		-
	3. After process solutions	0.90 (5.1)	-	-
Flexural Strength	A. Lengthwise direction	82,600	lb/inch ²	-
	B. Crosswise direction	66,400		
Tensile Strength	A. Lengthwise direction	60,890	lb/inch ²	-
	B. Crosswise direction	45,750		
Young's Modulus	A. Grain direction	3677	ksi	ASTM D790-15e2
	B. Fill direction	3179		
Poisson's Ratio	A. Grain direction	0.175	-	ASTM D3039-95a
	B. Fill direction	0.143		
Moisture Absorption		0.20	%	2.6.2.1
Flammability (Laminate & prepreg as laminated)		V-0	Rating	UL 94
Max Operating Temperature		130	°C	-

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

www.isola-group.com/products/IS410

The Isola name and logo are registered trademarks of Isola Corp. USA in the USA and other countries. All other trademarks mentioned herein are property of their respective owners. © 2015, Isola Group, All Rights Reserved.
03/17 DSIS410D

